(b) Amendments to the Specification

Please replace the Title at page 1, lines 1 and 2 with the following replacement Title:

--METHOD OF MANUFACTURING AN ELECTROCONDUCTIVE FILM, AND ~~AN APPARATUS INCLUDING~~ METHOD OF MANUFACTURING AN IMAGE FORMING APPARATUS INCLUDING THE ELECTROCONDUCTIVE FILM–

Please substitute the paragraph on page 7, lines 7-12 with the following replacement paragraph:

--For that reason, the curled amount of edge (B/A) is about twice. In the present specification, the curled amount of edge is directed to a ratio of B to A in ~~Figs. 13A to~~ Fig. 13D, and in this case, that the curled amount of edge is about twice means B/A = (18/10) to (12/10) ≅ 2.--

Please substitute the paragraph at page 11, lines 12-15 with the following replacement paragraph:

--removing non-exposed region of said laminate film where the photosensitive material is a negative type step or the exposed region of the laminate film where the photosensitive material is a positive type; and–

Please substitute the paragraph at page 15, lines 2-10 with the following replacement paragraph:

--Referring to Figs. 1A to 1E, reference numeral 11 denotes a substrate; 12 denotes a layer which is a film formed by coating a photosensitive paste on the substrate 11; 13 denotes a mask used for irradiating a light onto only a desired region of the layer 12; 14 and 17 denote exposure lights; 15 and 18 denote latent images formed by exposure; 19 denotes a ~~developing~~ developed pattern as a developer; and 20 denotes a completed wiring pattern (electroconductive film).--

Please substitute the paragraph at page 17, lines 14-17 with the following replacement paragraph:

--In the state where the exposure is ~~repeated~~ carried out twice as described above, the developing process is implemented on the photosensitive paste layer 12 having a height of about 13 μm in Fig. 1D.--

Please substitute the paragraph at page 22, lines 13-17 with the following replacement paragraph:

--In this way, the film forming process to the exposure process ~~are repeated~~ is carried out twice. The above processes are a process of forming a laminate film, and the latent images 15 and 18 are also laminated on each other.--

Please substitute the paragraphs at page 23, lines 2-6; page 23, lines 13-17 and beginning at page 23, line 23 and ending at page 24, line 4 with the following replacement paragraphs, respectively:

--In addition, as shown in Fig. 2F, a desired wiring pattern 20 is formed by baking. In this case, the baking is implemented at about 500°C. The thickness of the wiring pattern 20 that has been baked is 5 microns or more and preferably about 14 μm.–

--In this way, the film forming process to the exposure process ~~are repeated~~ is carried out twice, and the developing process is proceeded together in the state of the two-layer structure, thereby being capable of remarkably reducing the curling of edge.--

--Also because the ~~curing~~ curling of edge is reduced, the insulating layer having a sufficient insulating property can be formed without particularly increasing the number of insulating layers which will be laminated on each other in a following process. As a result, even in the formation of the upper-layer wiring on the insulating layer, there is no case in which the disconnection of the upper-layer wiring occurs at the step due to the curled edge.--

Please substitute the paragraph at page 27, lines 16-20 with the following replacement paragraph:

--In this way, the film forming process and the exposure process ~~are repeated~~ ~~third~~ is carried out three times, and the photosensitive paste having a height of about 22 μm is developed together in the state of the three-layer structure in Fig. 3G.--

Please substitute the paragraphs at page 28, lines 10-15 and beginning at page 28, line 24 and ending at page 29, line 2 with the following replacement paragraphs, respectively:

--In this way, the film forming process and the exposure process ~~are repeated third~~ are carried out three times, and the developing process and the subsequent processes are proceeded together in the state of the three-layer structure, thereby being capable of remarkably reducing the curling of edge.--

--Also, because the ~~curing~~ curling of edge is reduced, the number of processes is not increased because the number of insulating layers which will be laminated by several layers on each other in a following process does not increase, and also an excessive step is not produced in formation of the upper-layer wiring.--

Please substitute the paragraph beginning at page 29, line 23 and ending at page 30, line 2 with the following replacement paragraph:

--Referring to Figs. 4A to 4F, reference numeral 11 denotes a substrate; 12 and 16 denote first and second layers each formed by coating a photosensitive paste on the substrate 11; 13 and ~~31~~ 13' denote masks; 14 and 17 denote exposure lights; 15 and 18 denote latent images; 19 denotes a developing pattern; and 20 denotes a wiring pattern (electroconductive film).--

Please substitute the paragraph at page 30, lines 3-11 with the following replacement paragraph:

--In this embodiment, the masks 13 and ~~31~~ 13' used in the processes of Figs. 4B and 4D are different from each other, and more particularly the opening width is different between the masks 13 and ~~31~~ 13'. The wiring is fabricated in the same method as that of the second embodiment except that the narrower mask ~~31~~ 13' is used, and the developing pattern 19 different in the upper and lower line widths is finally fabricated as shown in Fig. 4E.--

Please substitute the paragraph beginning at page 30, line 24 and ending at page 31, line 2 with the following replacement paragraph:

--In this way, the film forming process and the exposure process ~~are repeated~~ is carried out twice, and the developing process and the subsequent processes are proceeded together in the state of the two-layer structure, thereby being capable of remarkably reducing the curling of edge.--

Please substitute the paragraphs at page 31, lines 5-10 and page 31, lines 11-16 with the following replacement paragraphs, respectively:

--In this way, because the ~~curing~~ curling of edge is reduced, the generation of bubbles is reduced even if the insulating layer is formed on the wiring pattern 20, and the generation of the hole or the growth of the bubbles is reduced even in the laminate layer.

Also, even if an electrode is further formed on the insulating layer, defects that lead to short-circuiting are remarkably reduced.--

--Also, because the ~~curing~~ curling of edge is reduced, the number of processes is not increased because the number of insulating layers which will be laminated by several layers on each other in a following process does not increase, and also an excessive step is not produced in formation of the upper-layer wiring.--

Please substitute the paragraphs at page 33, lines 12-17, page 33, lines 18-25 and beginning at page 33, line 26 and ending on page 34, line 8 with the following replacement paragraphs:

--In this way, the film forming process and the exposure process are ~~repeated~~ carried out three times , and the developing process and the subsequent processes are proceeded together in the state of the three-layer structure, thereby being capable of remarkably reducing the curling of edge.--

--In this way, because the ~~curing~~ curling of edge is reduced, the generation of bubbles is reduced even if the insulating layer is formed on the wiring pattern 25, and the generation of the hole or the growth of the bubbles is reduced even in the laminate layer. Also, even if an electrode is further formed on the insulating layer, defects that lead to short-circuiting are remarkably reduced.--

--Also, because the ~~curing~~ curling of edge is reduced, the number of processes is not increased because the number of insulating layers which will be laminated by several layers on each other in a following process does not increase, and also an excessive step is not produced in formation of the upper-layer wiring. Also, because the buildup of the curled edge portion is small even in the terminal portion, even if flexible mounting is conducted, the curled edge portion is not damaged, and the contact failure does not occur.--

Please substitute the paragraphs at page 36, lines 4-11 and page 36, lines 12-17 with the following replacement paragraphs, respectively:

--In this way, because ~~curing~~ curling of edge is reduced, the generation of bubbles is reduced even if the insulating layer is formed on the wiring pattern 20, and the generation of the hole or the growth of the bubbles is reduced even in the laminate layer. Also, even if an electrode is further formed on the insulating layer, defects that lead to short-circuiting are remarkably reduced.--

--Also, because the ~~curing~~ curling of edge is reduced, the number of processes is not increased because the number of insulating layers which will be laminated by several layers on each other in a following process does not increase, and also an excessive step is not produced in formation of the upper-layer wiring.--

Please delete the entire Abstract of the Disclosure section on page 53, lines 1-9 and insert a new Abstract of the Disclosure section instead of a replacement Abstract as set forth in the following separate sheet, pursuant to 37 C.F.R. §1.72.